Pin Description

TYPE					
I	INPUT	P	Power supply, GND	NC	NOT CONNECT
O	OUTPUT				
B	BIDIRECTION				

■ I^2C interface

I2CCK	B	I^2C Clock pin
I2CDT	B	I^2C Data pin

■D/A interface

BIASO	O	D/A output (Hall bias input)

■Op-Amp interface

OPINP	I	Op-Amp input
OPINM	I	Op-Amp input

■Driver interface

OUT1	O	Actuator output pin
OUT2	O	Actuator output pin

■Power supply pin

VDD	P	Digital power supply
VSS	P	Digital GND
VDDO	P	LDO power supply out
VM	P	Motor power supply
PGND	P	Power GND

PIN TYPE “O” – Ensure that it is set to OPEN.
PIN TYPE “I” – OPEN is inhibited. Ensure that it is connected to the V_{DD} or V_{SS} even when it is unused.
(Please contact our company for more information about selection of V_{DD} or V_{SS}.)
PIN TYPE “B” – If you are unsure about processing method on the pin description of pin layout table, please contact us.

Note that incorrect processing of unused pins may result in defects.
If you have any question, please feel free to contact us.

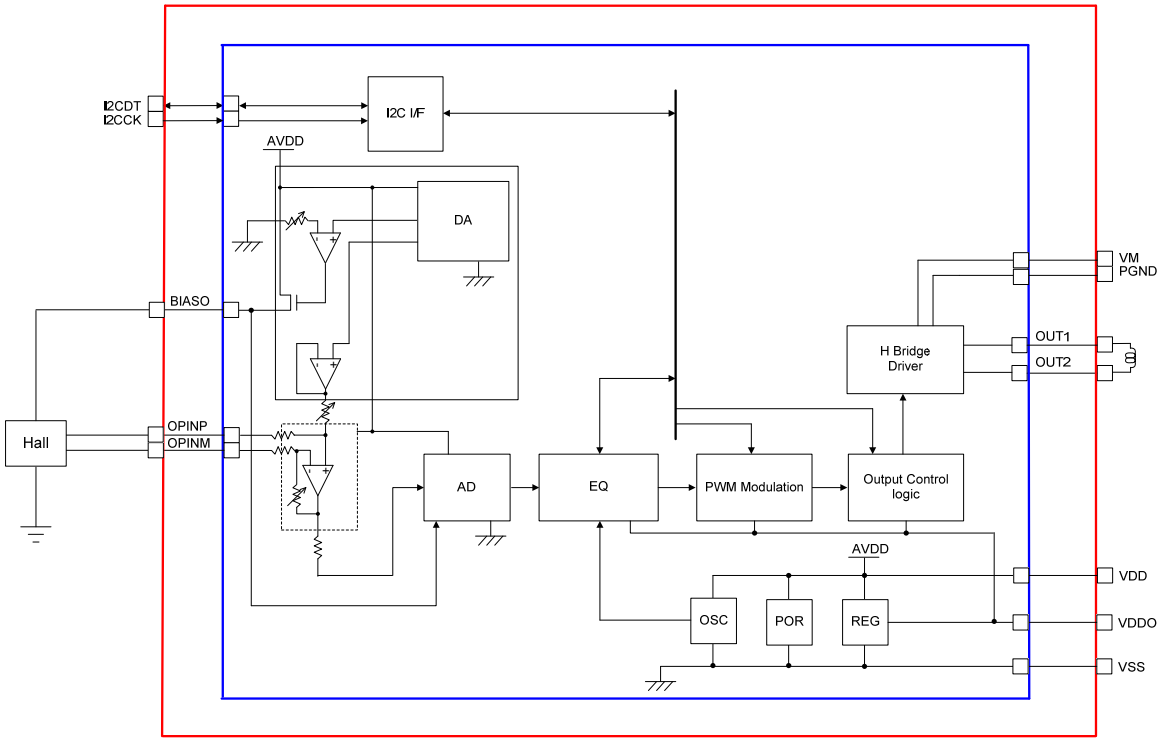
Pin Layout

Circuit Name	Number of Pins	Circuit Name	Number of Pins
Analog	4	Driver	4
Logic	4		

Backside pin layout diagram (Top View from the mold side)

	A	B	C
4	VDDO	VM	PGND
3	AVDD	I2CDT	OUT1
2	OPINP	I2CCK	OUT2
1	VSS	OPINM	BIASO

Block Diagram

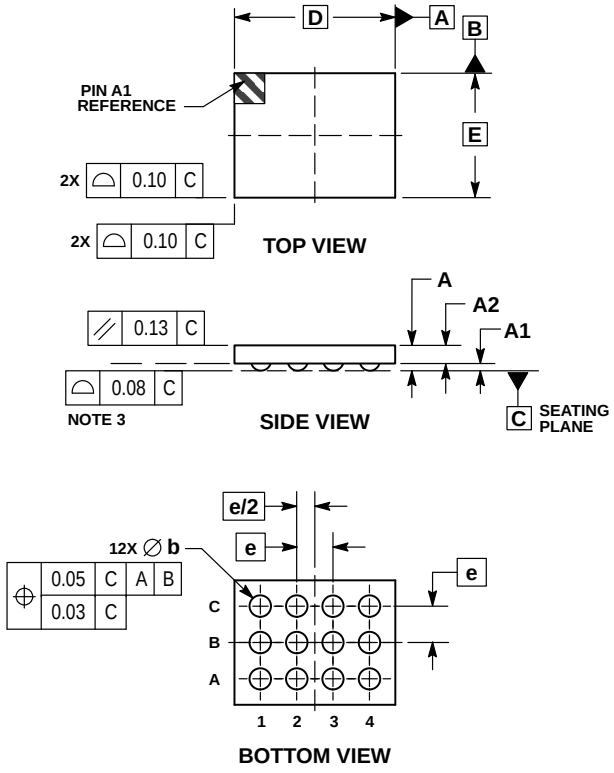


Package Dimensions

WLP12J(1.77X1.37)

unit : mm

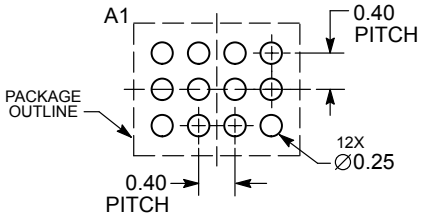
WLCSP12, 1.77x1.37
CASE 567GH
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS MIN	MAX
A	---	0.33
A1	0.03	0.13
A2	0.20 REF	
b	0.15	0.25
D	1.77 BSC	
E	1.37 BSC	
e	0.40 BSC	

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)
LC898212XD-SH	WLP12J(1.77X1.37) (Pb-Free / Halogen Free)	5000 / Tape & Reel